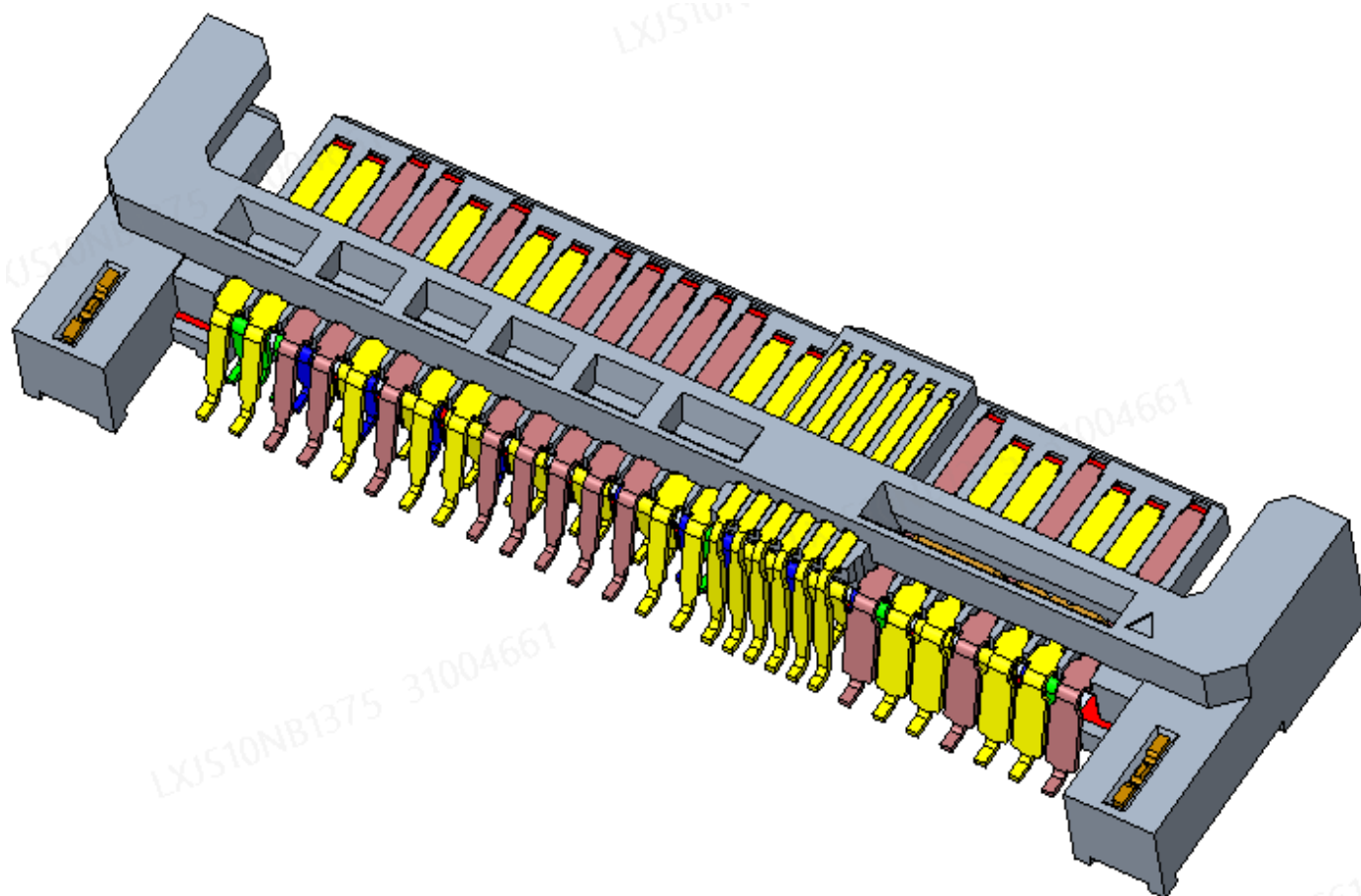


SFF-8639 PCIe5.0 PLUG CONN



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2026/07/10

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1 OBJECTIVE

This specification provides information and requirements regarding customer application of the SFF-8639 PCIe5.0 PLUG CONN. This specification is intended to provide general guidance for application process development. It is recognized that no single application process will work under all customer scenarios and that customers will develop their own application processes to meet their needs. However, if the application process differ greatly from the one recommended, Luxshare cannot guarantee results.

2 SCOPE

This specification provides information and requirements regarding customer installation and reworking process of the SFF-8639 PCIe5.0 PLUG CONN.

3 DRAWINGS AND APPLICABLE DOCUMENTS

- Luxshare Product Specification:
- Application Luxshare Customer Drawings;
- Luxshare Application Specification:

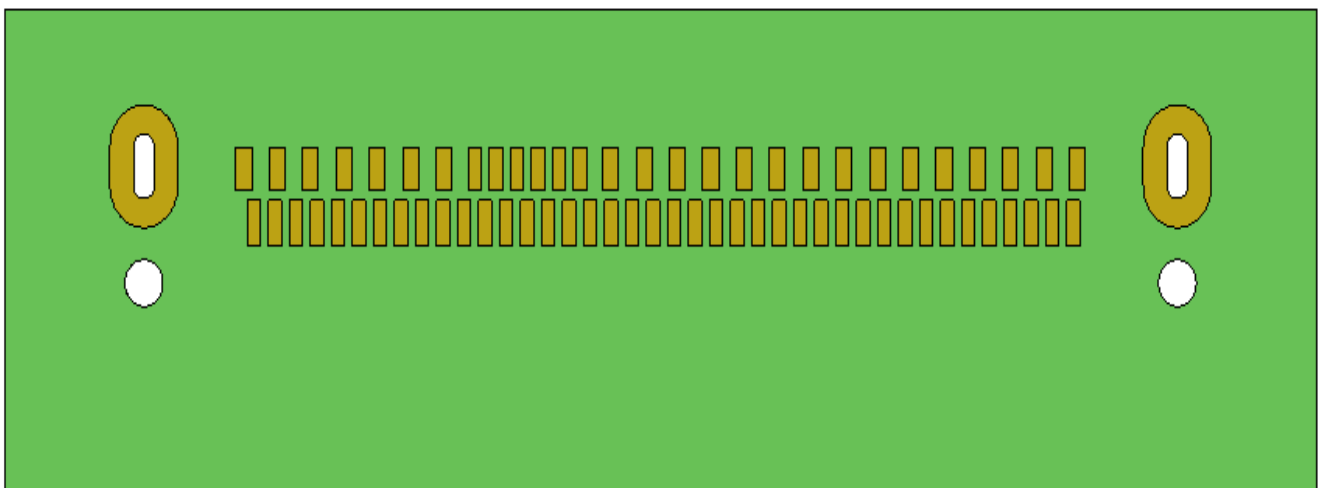
In the event of a conflict between this application specification and the drawing, the drawing will take precedence. Customers are advised to refer to the latest revision of Luxshare product drawings for appropriate details.

4 INSTALLATION PROCESS

This document is meant to be an application guide. If there is a conflict between the product drawings and specifications, the drawings take precedence.

4.1 CONNECTOR SMT PROCESS

- 4.1.1 Brush solder paste: Apply an even layer of solder paste to the solder pad (terminals, PAD, etc.) of the connector to be soldered.

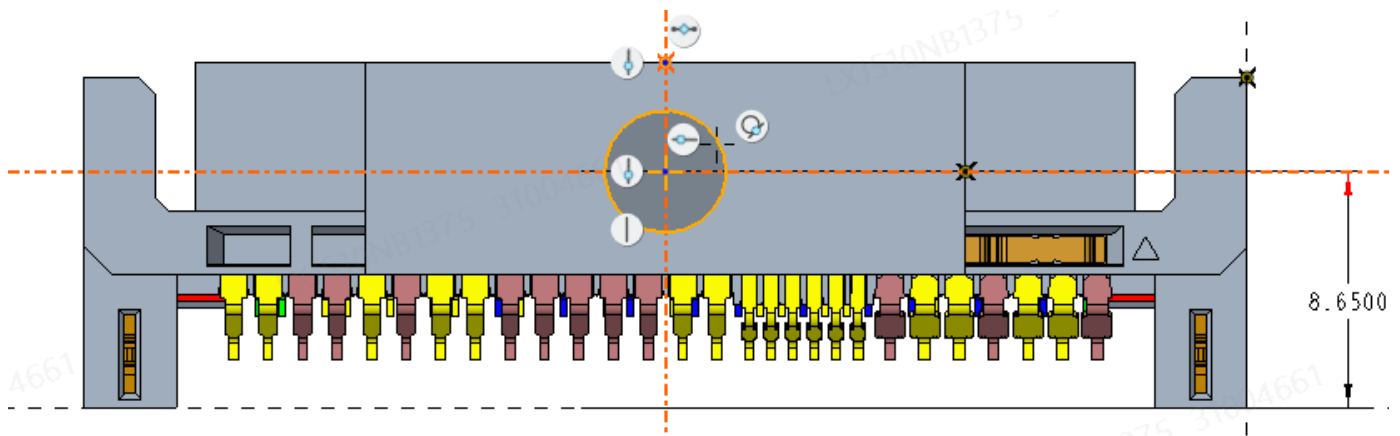


a. Recommended soldering sequence: If soldering upside down, the first side must be protected from falling. (it is recommended that a fixture is used) Meanwhile, it is recommended that to use glue to fix the first side connector.

b. Recommended the stencil thickness is 0.15mm.

4.1.2 Pick and place: When the connector is absorbed into the pad, the suction nozzle shall be placed in the pick-up area on the top of the connector.

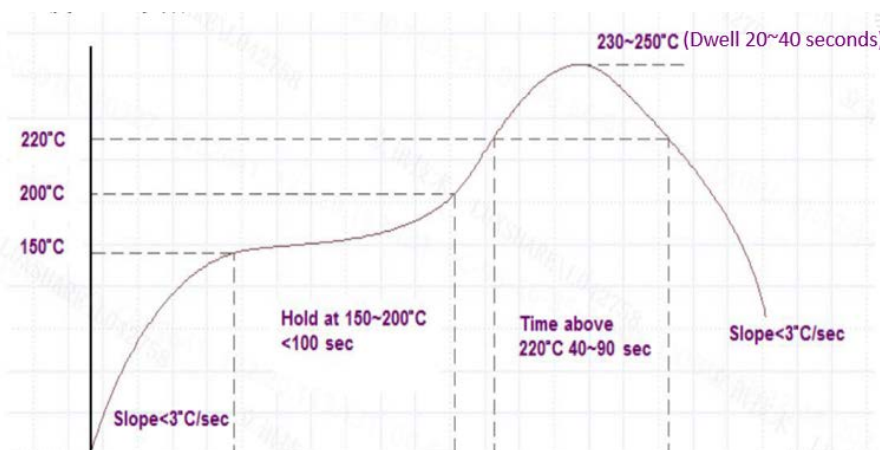
10~15N of press force is recommended.



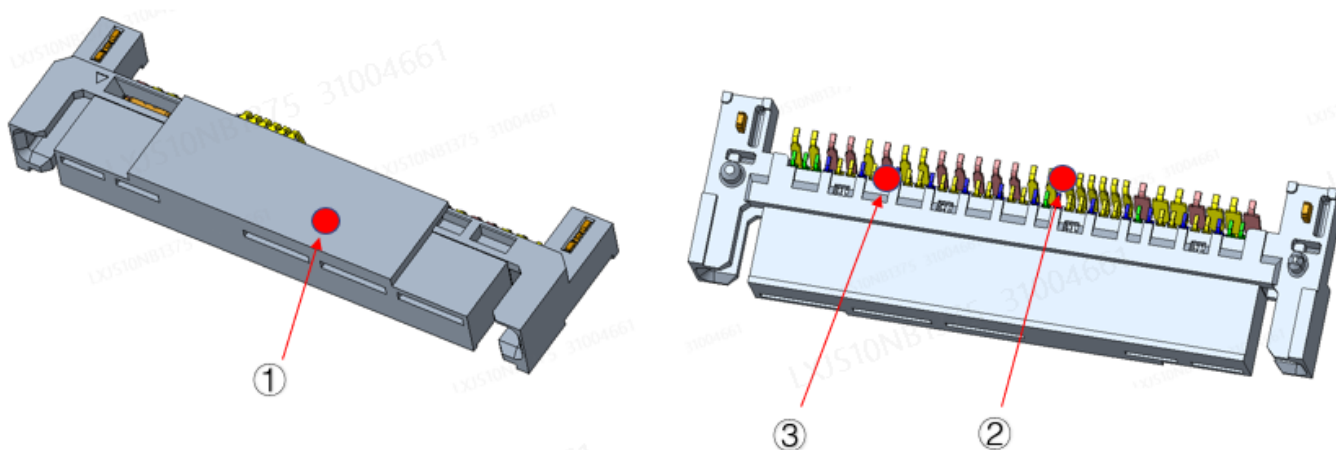
4.1.3 IR Reflow



a. Recommended reflow profile below.

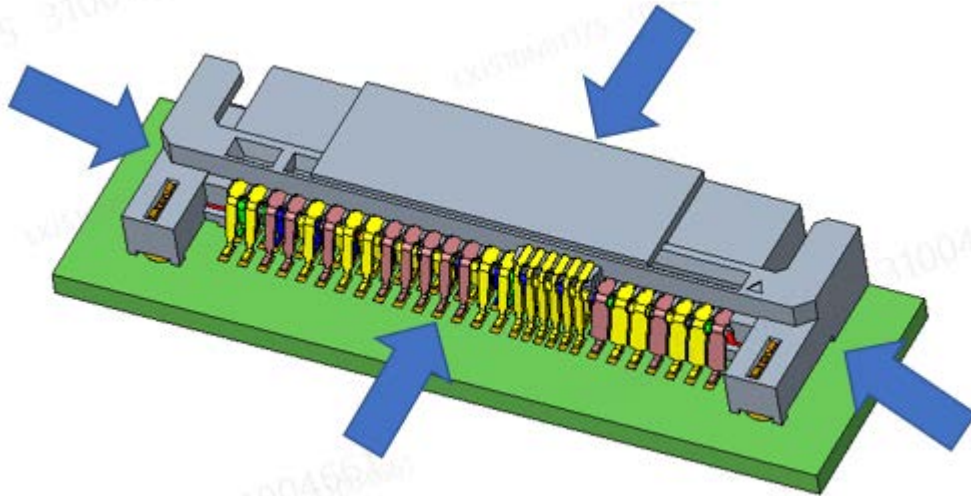


- b. Recommended to use reflow welding furnace above 8 temperature zone (nitrogen protection measures are recommended)
- c. Recommended thermocouple locations.



Point1: temperature of oven
Point2: temperature of connector's outside tails
Point3: temperature of connector's inside tails

- d. The reflow process need to use nitrogen and oxygen concentration is within 3000PPM.



5 Rework Process

5.1 Connector unsoldering

- Heat connector solder to molten state, then remove the connector lightly.
- To minimize damage to PCB and components, if allows, heat the connector from underneath.



TYPE
**PRODUCT APPLICATION
SPECIFICATION**

SPEC. NO
Revision.
A1

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REVISION RECORD

Rev	Page	Description	EC#	Date
A1	All	Release specification		2026/7/10